High Power Switching and Attenuation Silicon PIN Diodes

Features
- Fast Switching
- Low Series Resistance
- Low Junction Capacitance
- Low Thermal Resistance
- RoHS* Compliant

Applications
- ISM

Description
The MMP7060 - 69 Series of PIN diodes are fast switching, low series resistance, low capacitance PIN diode chips. These diodes are also available packaged in several other package styles. The low junction capacitance, thin I-layer and low series resistances combine to produce outstanding insertion loss, isolation and switching time. The low thermal resistance enables these devices to safely handle moderately high power signals in high frequency switching applications. These rugged devices are capable of reliable operation in all military, commercial and industrial applications.

This series of PIN diodes are designed to be used in moderate peak and average power switch applications which operate at high frequencies and require low switching time. These diodes performs exceptionally well from UHF through microwave frequencies.

<table>
<thead>
<tr>
<th>Dimension</th>
<th>Min.</th>
<th>Nom.</th>
<th>Max.</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>0.012</td>
<td>0.013</td>
<td>0.014</td>
</tr>
<tr>
<td>B</td>
<td>0.012</td>
<td>0.013</td>
<td>0.014</td>
</tr>
<tr>
<td>C</td>
<td>0.004</td>
<td>0.005</td>
<td>0.006</td>
</tr>
<tr>
<td>D</td>
<td>0.003</td>
<td>0.004</td>
<td>0.005</td>
</tr>
</tbody>
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Consult Factory for other package styles.

* Restrictions on Hazardous Substances, compliant to current RoHS EU directive.
Environmental Capabilities

The MMP706x-11 Series of PIN diodes are capable of meeting the environmental requirements of MIL-STD-750 and MIL-STD-883.

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these (HBM) Class 0 devices.

Assembly Instructions

Die attach of MMP706x silicon PIN diode chips may be accomplished with conductive epoxy or a eutectic solder such as Au(80%)/Sn(20%) or Au(88%)/Ge(12%). Electrical connection to the cathode may be made with a Au wire or ribbon, utilizing thermo compression or thermosonic bonding. Care should be exercised to not employ excessive pressure or ultrasonic energy while wire/ribbon bonding to avoid physical damage to the die.
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